

●SOP-8FD Power Dissipation

Power dissipation data for the SOP-8FD is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

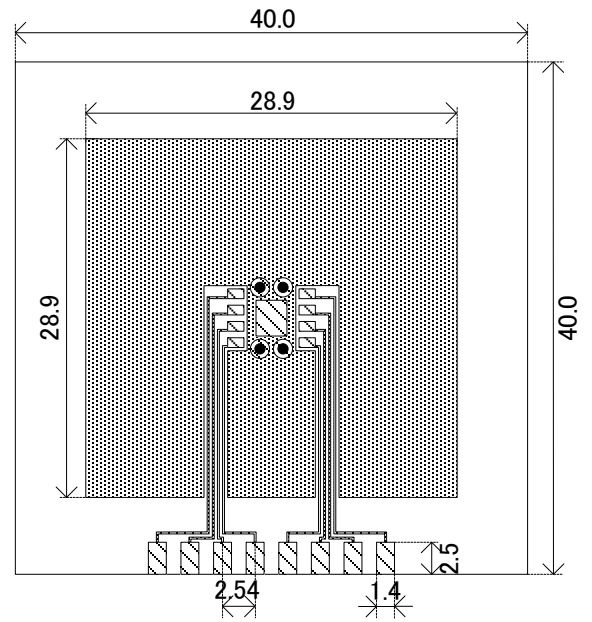
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

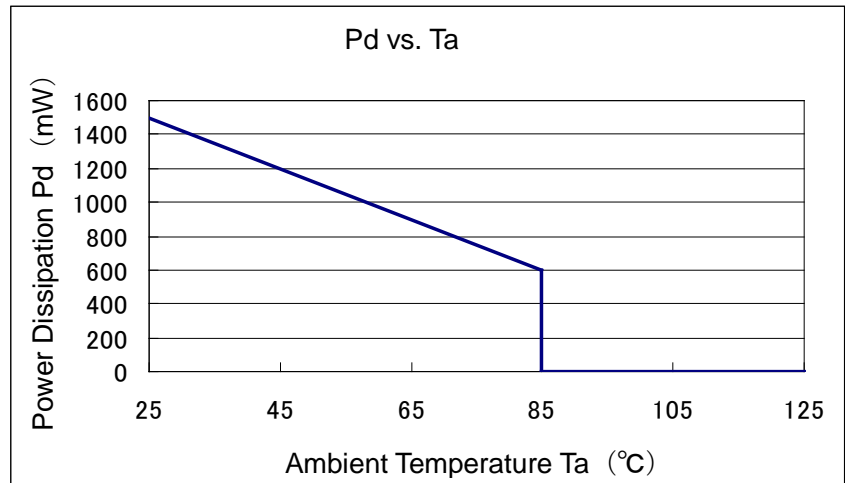


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature (85°C)

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

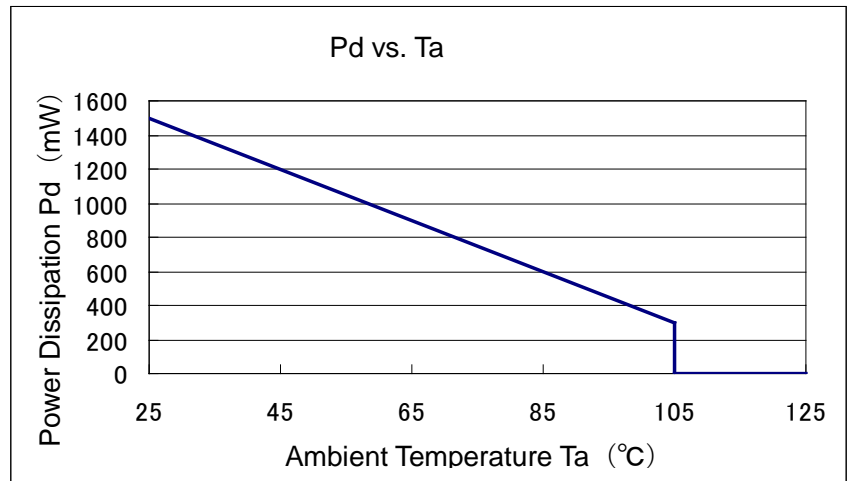
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1500	66.67
85	600	



3. Power Dissipation vs. Ambient temperature (105°C)

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1500	66.67
105	300	

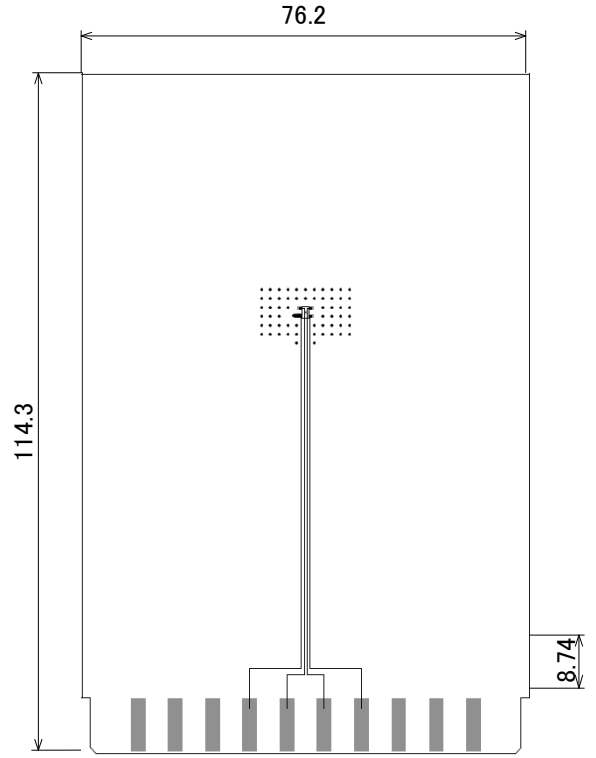


●SOP-8FD Power Dissipation (JESD51-7)

Power dissipation data for the SOP-8FD is shown in this page.
 The value of power dissipation varies with the mount board conditions.
 Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: 76.2mm × 114.3mm (8700mm² in one side)
 - 1st inner layer: No copper foil
 - Package heat-sink is tied to the copper traces
 - 2nd inner layer: 70mm × 70mm_ with heat sink
 - 3rd inner layer: 70mm × 70mm_ with heat sink
 - 4th inner layer: No copper foil
 - Each heat sink back metal is connected to the Inner layers respectively.
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 60 x 0.2 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature (125°C)

Board Mount (T_j max = 125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	2500	40.00
105	500	

